PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Rao Venkateswara Annapragada	04/06/2000

RECEIVING PARTY DATA

Name:	VLSI Technology, Inc.
Street Address:	1109 McKay Drive
City:	San Jose
State/Country:	CALIFORNIA
Postal Code:	95131

PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	6876063

CORRESPONDENCE DATA

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

via US Mail.

Correspondent Name: David L. Schaeffer

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Address Line 2: NXP Semiconductors, IP&L
Address Line 4: San Jose, CALIFORNIA 95134

NAME OF SUBMITTER: David L. Schaeffer

Total Attachments: 1

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CH \$40.00

PATENT REEL: 027128 FRAME: 0322

Assignment to VLSI Technology, Inc.

In consideration of good and valuable consideration, receipt of which is hereby acknowledged, I/we Rao Venkateswara Annapragada do hereby sell, assign and transfer unto VLSI Technology, Inc. (hereinafter called VLSI), a California Corporation having its principal place of business at 1109 McKay Drive, San Jose, California 95131, and its successors and assigns, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements, including the right of priority in, to, and under, the application for the United States patent entitled: A METHOD OF IMPROVING ADHESION OF CAP OXIDE TO NANOPOROUS SILICA FOR INTEGRATED CIRCUIT FABRICATION x filed herewith and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore; or Serial No.: filed on and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore; Further, I/we have agreed to assign to VLSI all inventions (except as otherwise limited by law) which relate to VLSI business and which were first conceived or actually reduced to practice during my/our employment by VLSI; And for the above consideration, I/we agree promptly upon request of VLSI, its successors or assigns, to execute and deliver without further compensation any power of attorney, assignment, application, whether original, continuation, divisional or reissue, or other papers which may be necessary or desirable fully to secure to VLSI, its successors and assigns, the inventions described in said application and all patent rights therein, in the United States and in any country foreign thereto, and to cooperate and assist in the prosecution of interference proceedings involving said inventions and in the adjudication or reexamination of said Letters Patent provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by VLSI; I/we further covenant with VLSI, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned; In witness whereof, I/we hereunto set my/our hand(s) and seal. Inventor's Signature: \ Rac Annaprageda Date: 4/6/00

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PATENT REEL: 01076AFRMME: 0297 REEL: 027128 FRAME: 0323